NTD5804N

Power MOSFET
40 V, 69 A, Single N−Channel, DPAK

Features
- Low $R_{DS(on)}$
- High Current Capability
- Avalanche Energy Specified
- These are Pb−Free Devices

Applications
- CCFL Backlight
- DC Motor Control
- Class D Amplifier
- Power Supply Secondary Side Synchronous Rectification

ON Semiconductor®

http://onsemi.com

$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX
40 V	12 mΩ @ 5.0 V	69 A
	8.5 mΩ @ 10 V	

N−CHANNEL MOSFET

DPAK CASE 369C (Surface Mount) STYLE 2
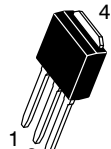
DPAK CASE 369D (Straight Lead) STYLE 2

MARKING DIAGRAMS & PIN ASSIGNMENT

Y	= Year
WW	= Work Week
5804N	= Device Code
G	= Pb−Free Package

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	40	V
Gate−to−Source Voltage − Continuous			V_{GS}	± 20	V
Gate−to−Source Voltage − Non−Repetitive (t_p < 10 μS)			V_{GS}	± 30	V
Continuous Drain Current ($R_{θJC}$) (Note 1)	Steady State	T_C = 25°C	I_D	69	A
		T_C = 100°C		49	
Power Dissipation ($R_{θJC}$) (Note 1)		T_C = 25°C	P_D	71	W
Pulsed Drain Current	t_p = 10 μs		I_{DM}	125	A
Operating Junction and Storage Temperature			T_J, T_{stg}	−55 to 175	°C
Source Current (Body Diode)			I_S	30	A
Single Pulse Drain−to−Source Avalanche Energy (V_{DD} = 50 V, V_{GS} = 10 V, R_G = 25 Ω, $I_{L(pk)}$ = 36 A, L = 0.3 mH, V_{DS} = 40 V)			E_{AS}	195	mJ
Lead Temperature for Soldering Purposes (1/8″ from case for 10 s)			T_L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction−to−Case (Drain)	$R_{θJC}$	2.1	°C/W
Junction−to−Ambient − Steady State (Note 1)	$R_{θJA}$	106	

1. Surface−mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces.
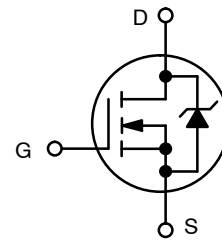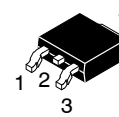
ORDERING INFORMATION

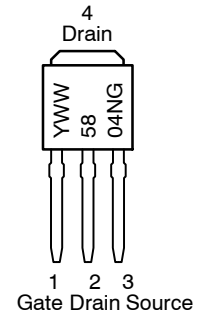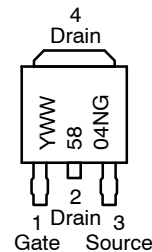See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA		40	45		V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$				41		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 40 V	T_J = 25°C			1.0	μA
			T_J = 150°C			100	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V				±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250 μA		1.5		3.5	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$				7.3		mV/°C
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 30 A			5.7	8.5	mΩ
		V_{GS} = 5 V, I_D = 10 A			7.9	12	
Forward Transconductance	gFS	V_{DS} = 15 V, I_D = 15 A			12		S
CHARGES, CAPACITANCES AND GATE RESISTANCES							
Input Capacitance	C_{iss}	V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = 25 V			2460	2850	pF
Output Capacitance	C_{oss}				310	400	
Reverse Transfer Capacitance	C_{rss}				215	280	
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 10 V, V_{DS} = 32 V, I_D = 30 A			45		nC
Threshold Gate Charge	$Q_{G(TH)}$				2.8		
Gate−to−Source Charge	Q_{GS}				10		
Gate−to−Drain Charge	Q_{GD}				12.6		
SWITCHING CHARACTERISTICS (Note 3)							
Turn−On Delay Time	$t_{d(on)}$	V_{GS} = 10 V, V_{DD} = 32 V, I_D = 30 A, R_G = 2.5 Ω			11.8		ns
Rise Time	t_r				18.7		
Turn−Off Delay Time	$t_{d(off)}$				26.8		
Fall Time	t_f				5.9		
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, I_S = 10 A	T_J = 25°C		0.81	1.2	V
			T_J = 150°C		0.63		
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, dIs/dt = 100 A/μs, I_S = 30 A			21.7		ns
Charge Time	ta				11.9		
Discharge Time	tb				9.8		
Reverse Recovery Charge	Q_{RR}				11.8		nC

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
3. Switching characteristics are independent of operating junction temperatures.
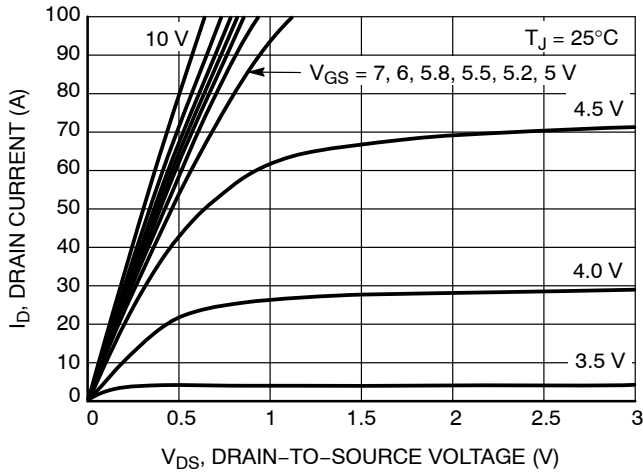
TYPICAL CHARACTERISTICS
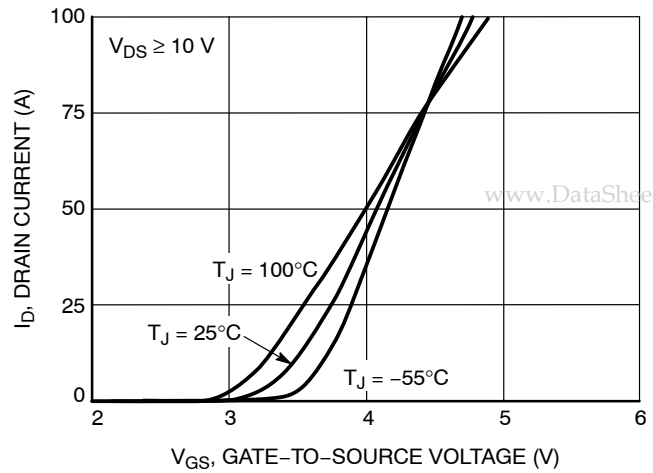

Figure 1. On−Region Characteristics

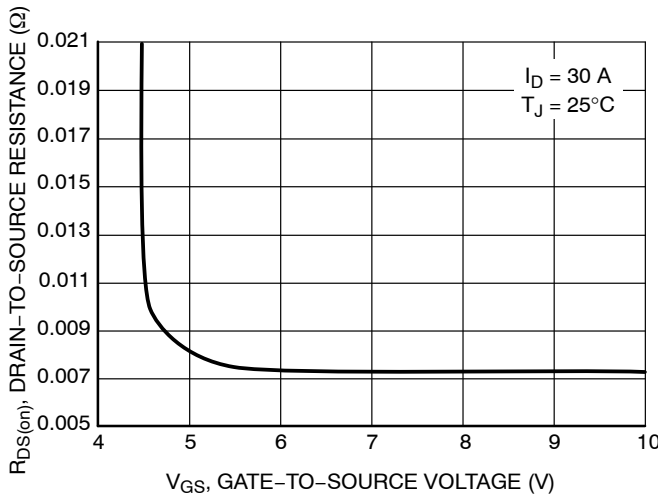Figure 2. Transfer Characteristics

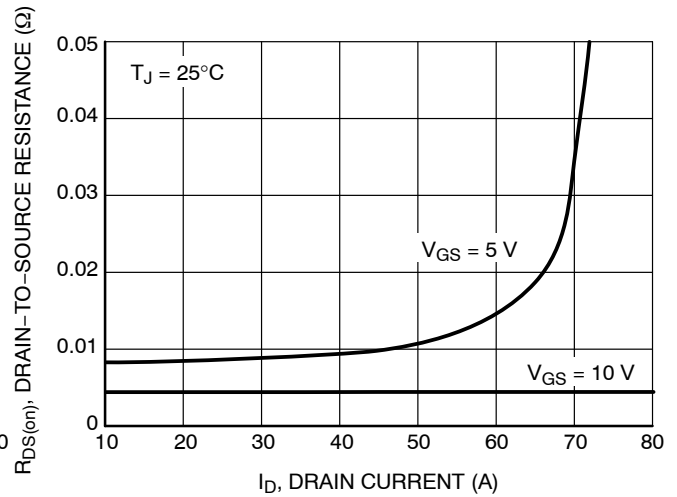Figure 3. On−Resistance vs. Drain Current

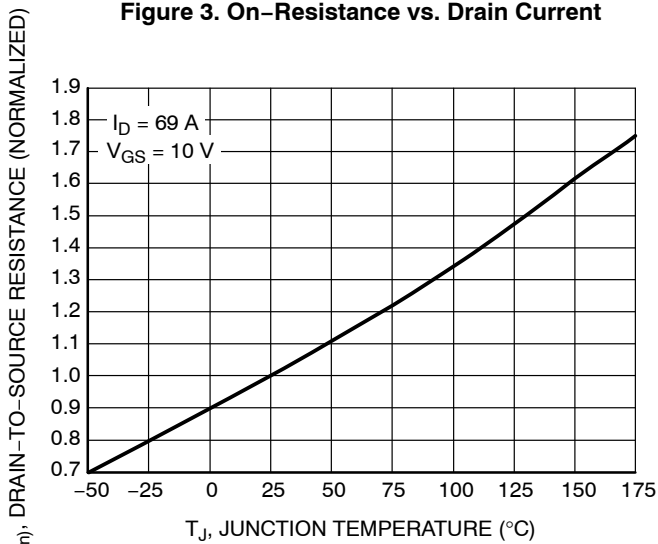Figure 4. On−Resistance vs. Drain Current and Gate Voltage

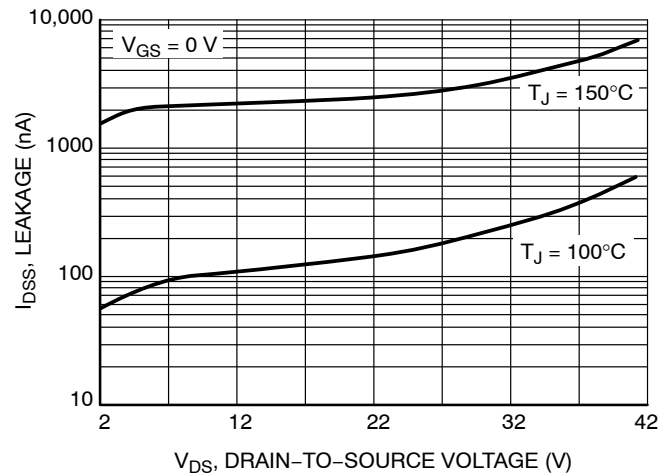Figure 5. On−Resistance Variation with Temperature

Figure 6. Drain−to−Source Leakage Current vs. Voltage
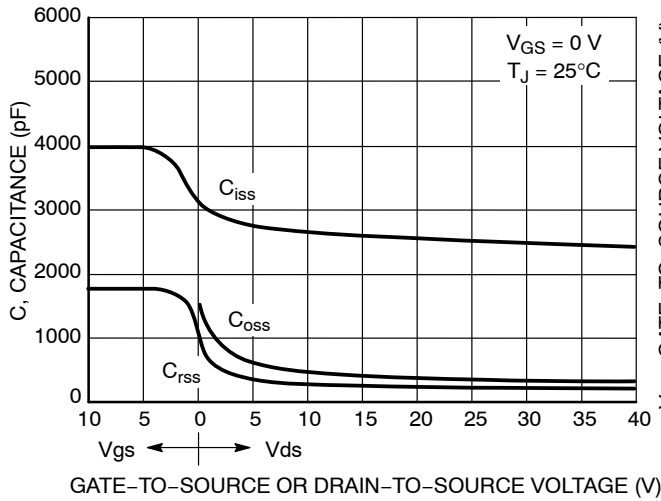
NTD5804N

TYPICAL CHARACTERISTICS
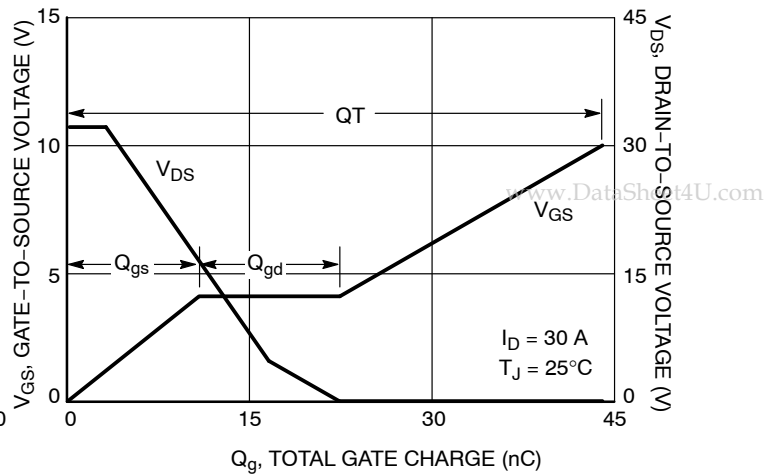

Figure 7. Capacitance Variation

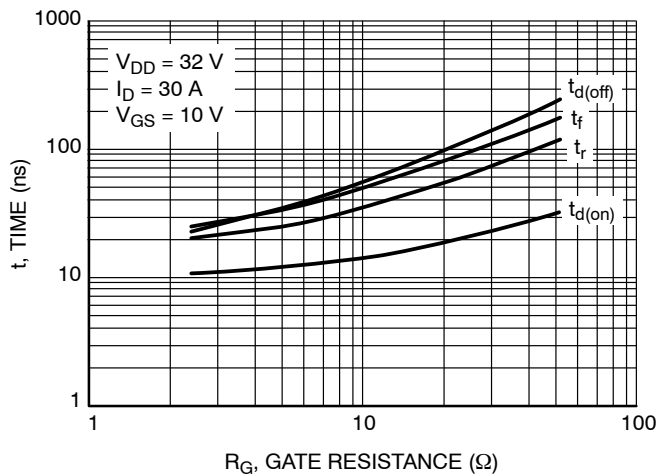**Figure 8. Gate−to−Source and Drain−to−Source Voltage vs. Total Charge**

Figure 9. Resistive Switching Time Variation vs. Gate Resistance
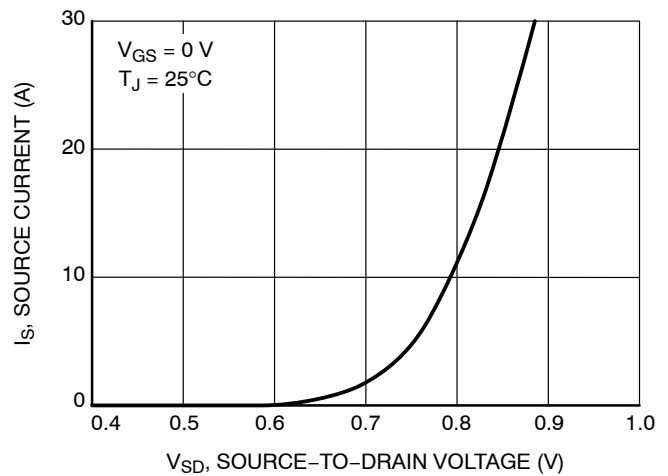
Figure 10. Diode Forward Voltage vs. Current

ORDERING INFORMATION

Order Number	Package	Shipping†
NTD5804NG	DPAK (Straight Lead) (Pb−Free)	75 Units / Rail
NTD5804NT4G	DPAK (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK
CASE 369C–01
ISSUE O
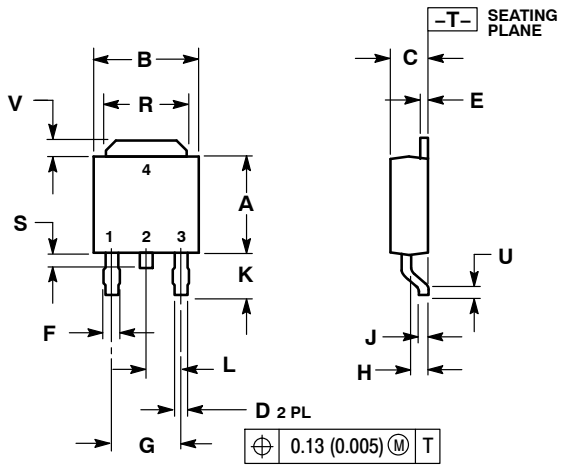
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020	–––	0.51	–––
V	0.035	0.050	0.89	1.27
Z	0.155	–––	3.93	–––

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*
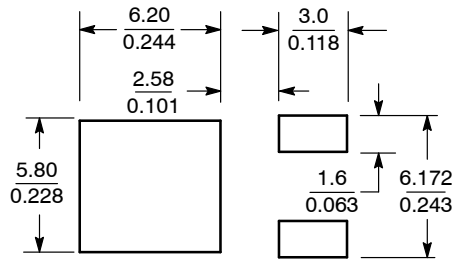
SCALE 3:1 $\left(\dfrac{mm}{inches}\right)$

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NTD5804N

PACKAGE DIMENSIONS

DPAK
CASE 369D–01
ISSUE B
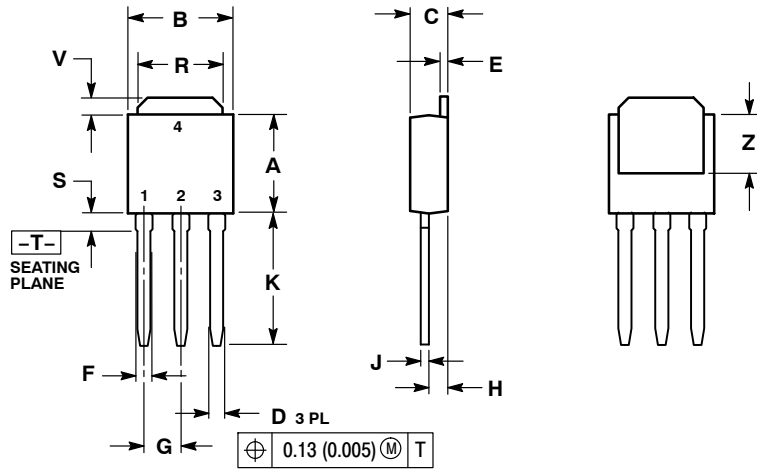
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D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	–––	3.93	–––

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

⊕ | 0.13 (0.005) Ⓜ | T

D 3 PL

SEATING PLANE

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